

# IGBT die nomenclature

IR G 4 C C 5 0 U CDV

## Device type

G = IGBT chip

## Technology

5 = Gen 5

4 = Gen 4

Blank = Gen 3

## Package type

C = No package (chip only)

## Voltage

C = 600V

H = 1200V

## Die size

3 = Die size 3

4 = Die size 4

5 = Die size 5

## Lead option

A = Lead form down\*

B = Lead form up

C = Lead trimmed (clipped)

*\*Lead attach if package is SMD*

## Screening level

SCX = TXlevel

SCV = TXVlevel

SCS = Space level

## Speed

U = Ultra fast

F = Fast

S = Standard